



Material Content Data Sheet



Sales Product Name		BSZ0503NSI		Issued		24. January 2018		
MA#		MA001295950						
Package		PG-TSDSON-8-25		Weight*		34.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.267	0.77	0.77	7733	7733
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		105	
	non noble metal	zinc	7440-66-6	0.015	0.04		421	
	non noble metal	iron	7439-89-6	0.291	0.84		8428	
wire	non noble metal	copper	7440-50-8	11.804	34.22	35.11	342216	351170
	non noble metal	copper	7440-50-8	0.017	0.05	0.05	479	479
	encapsulation	organic material	carbon black	1333-86-4	0.036	0.11		1055
	plastics	epoxy resin	-	1.874	5.43		54325	
	inorganic material	silicondioxide	60676-86-0	16.283	47.21	52.75	472049	527429
leadfinish	non noble metal	tin	7440-31-5	0.400	1.16	1.16	11602	11602
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	589	589
solder	noble metal	silver	7440-22-4	0.011	0.03		324	
	non noble metal	tin	7440-31-5	0.009	0.03		259	
	non noble metal	lead	7439-92-1	0.427	1.24	1.30	12382	12965
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		106	
	non noble metal	iron	7439-89-6	0.073	0.21		2113	
	non noble metal	copper	7440-50-8	2.959	8.58	8.80	85788	88033
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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